



Product Summary

V _{(BR)DSS}	R _{DS(ON)}	I _D T _A = +25 ℃
60V	1.8Ω @ V _{GS} = 10V	440mA
001	2.1Ω @ V _{GS} = 4.5V	410mA

Description

This new generation MOSFET is designed to minimize the on-state resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

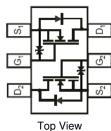
- Battery Operated Systems and Solid-State Relays
- Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories, Transistors, etc.
- DC-DC Converters
- Power Management Functions





Top View

Bottom View



Pin Definition/Schematic

Ordering Information (Note 5)

Part Number	Case	Packaging
DMG1026UVQ-7	SOT563	3,000 / Tape & Reel

SOT563

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

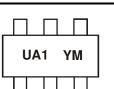
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to http://www.diodes.com/quality/product_grade_definitions/.

5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



UA1 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: X = 2010) M = Month (ex: 9 = September)

Date Code Key

Dale Coue Rey												
Year	2009		2010	2011		2012	2013		2014	2015		2016
Code	W		Х	Y		Z	A		В	C		D
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

DUAL N-CHANNEL ENHANCEMENT MODE MOSFET

Features

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

Mechanical Data

- Case: SOT563
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram Below
- Weight: 0.006 grams (Approximate)



Maximum Ratings (@T_A = +25 $^{\circ}$ C, unless otherwise specified.)

Characteri	Symbol	Value	Unit		
Drain-Source Voltage	V _{DSS}	60	V		
Gate-Source Voltage	V _{GSS}	±20	V		
Continuous Drain Current (Note 6) $V_{GS} = 10V$	Steady State	T _A = +25 ℃ T _A = +85 ℃	ID	410 300	mA
Continuous Drain Current (Note 7) $V_{GS} = 10V$	t≤10s	T _A = +25 ℃ T _A = +85 ℃	ID	440 320	mA
Continuous Drain Current (Note 6) $V_{GS} = 4.5V$	Steady State	T _A = +25 ℃ T _A = +85 ℃	ID	380 270	mA
Continuous Drain Current (Note 7) $V_{GS} = 4.5V$	t ≤ 10s	T _A = +25 ℃ T _A = +85 ℃	ID	410 295	mA
Pulsed Drain Current (Note 8)	I _{DM}	1.0	A		

Thermal Characteristics

Characteristic	Symbol	Max	Unit
Power Dissipation (Note 6)	PD	0.58	W
Thermal Resistance, Junction to Ambient @T _A = +25 °C (Note 6)	R _{0JA}	213	°C/W
Power Dissipation (Note 7) t \leq 10s	PD	0.65	W
Thermal Resistance, Junction to Ambient @T _A = +25 °C (Note 7) t \leq 10s	R _{0JA}	192	°C/W
Operating and Storage Temperature Range	TJ, TSTG	-55 to +150	C

Electrical Characteristics (@T_A = +25 °C, unless otherwise specified.)

Characteristic	Cumahal	Min	Tura	Мах	Unit	Test Condition
	Symbol	MIN	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 9)		r	1	r	1	
Drain-Source Breakdown Voltage	BV _{DSS}	60	—	_	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current T _J = +25℃	I _{DSS}			1.0	μA	$V_{DS}=50V,\ V_{GS}=0V$
Gate-Source Leakage	lass		—	±50	nA	$V_{GS}=\pm 5V, \ V_{DS}=0V$
	I _{GSS}		—	±150	nA	$V_{GS}=\pm 10V, \ V_{DS}=0V$
ON CHARACTERISTICS (Note 9)						
Gate Threshold Voltage	V _{GS(th)}	0.5	_	1.8	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$
Static Drain-Source On-Resistance	Design		1.2	1.8	Ω	$V_{GS} = 10V, I_D = 500mA$
Static Drain-Source On-Resistance	R _{DS (ON)}		1.4	2.1	12	$V_{GS} = 4.5V, I_D = 200mA$
Forward Transfer Admittance	Y _{fs}	80	580	—	mS	$V_{DS} = 10V, I_D = 200mA$
Continuous Source Current (Note 9)	I _S	—		200	mA	-
Diode Forward Voltage	V _{SD}	—	0.8	1.3	V	$V_{GS} = 0V, I_{S} = 200mA$
DYNAMIC CHARACTERISTICS (Note 10)	•					
Input Capacitance	C _{iss}		32	—		
Output Capacitance	C _{oss}	—	4.4	—	pF	V _{DS} = 25V, V _{GS} = 0V, f = 1.0MHz
Reverse Transfer Capacitance	Crss		2.9	-		
Gate Resistance	Rg		126	-	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$
Total Gate Charge	Qg	—	0.45	—		
Gate-Source Charge	Q _{gs}	—	0.08	—	рС	$V_{GS} = 4.5V, V_{DS} = 10V,$
Gate-Drain Charge	Q _{gd}		0.08	—		$I_D = 250 \text{mA}$
Turn-On Delay Time	t _{D(on)}	—	3.4	—	ns	
Turn-On Rise Time	tr	—	3.4	—	ns	$V_{GS} = 10V, V_{DS} = 30V,$
Turn-Off Delay Time	t _{D(off)}		26.4	—	ns	R _L = 150Ω, R _G = 25Ω, I _D = 200mA
Turn-Off Fall Time	t _f	_	16.3	—	ns	

Notes:

6. Device mounted on FR-4 PCB with minimum recommended pad layout, single sided. 7. Device mounted on FR-4 PCB with minimum recommended pad layout, measured in t \leq 10s.

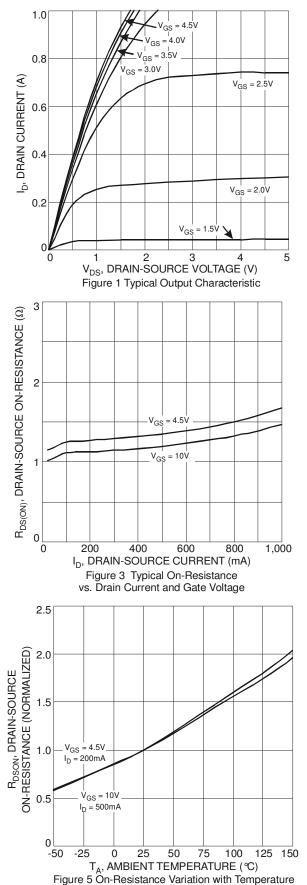
8. Repetitive rating, pulse width limited by junction temperature, 10µs pulse, duty cycle = 1%

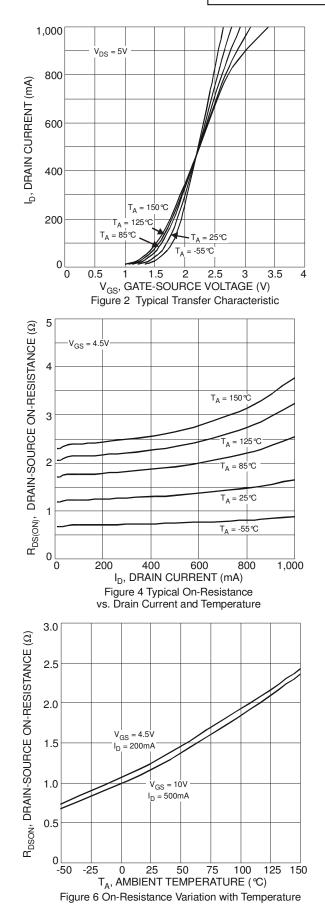
9. Short duration pulse test used to minimize self-heating effect.

10. Guaranteed by design. Not subject to production testing.



DMG1026UVQ







DMG1026UVQ

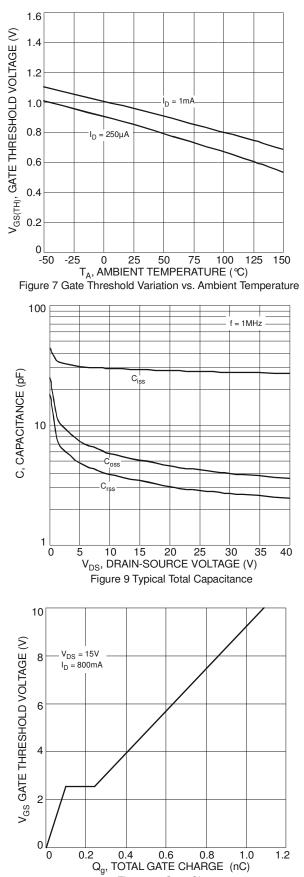
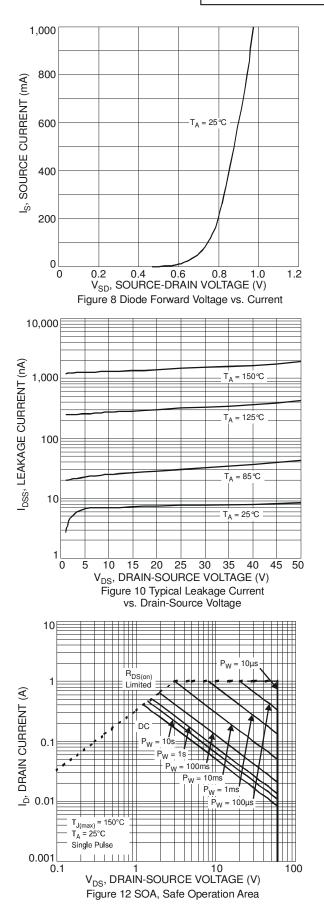
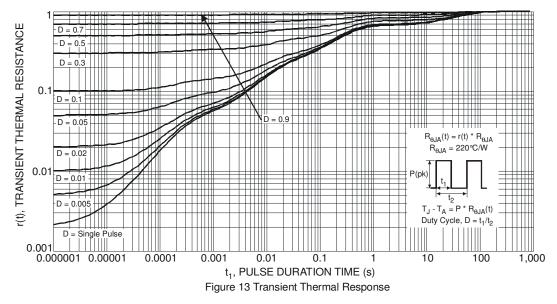


Figure 11 Gate Charge

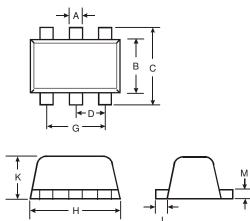






Package Outline Dimensions

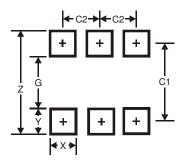
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



SOT563						
Dim	Min	Max	Тур			
Α	0.15	0.30	0.20			
в	1.10	1.25	1.20			
С	1.55	1.70	1.60			
D	-	-	0.50			
G	0.90	1.10	1.00			
Н	1.50	1.70	1.60			
Κ	0.55	0.60	0.60			
L	0.10	0.30	0.20			
М	0.10	0.18	0.11			
All Dimensions in mm						

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	2.2
G	1.2
Х	0.375
Y	0.5
C1	1.7
C2	0.5



IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes Incorporated.

LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
 - 1. are intended to implant into the body, or
 - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2015, Diodes Incorporated

www.diodes.com